

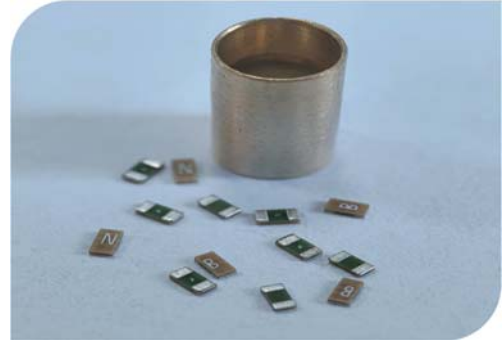
## Ultra-Thin Fuse | 0.06x0.03"

## 0603TD-L Series

### Time Delay series Thin Film Chip Fuse

#### Features

- Low DCR
- High inrush current withstanding capability
- High reliability
- Fiberglass enforced epoxy fuse body
- Copper termination with nickel and tin plating layer
- Halogen free, RoHS compliance & lead-free



#### Application

- Panel
- HDD
- Toy
- IoT
- Battery pack
- Finger print
- Smart lock
- Notebook

#### Electrical Characteristics

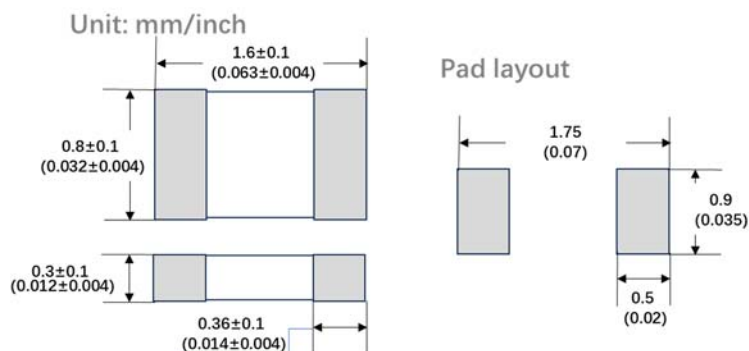
| % of Current Rating | Opening Time   |
|---------------------|----------------|
| 100%                | 4hours min.    |
| 200%                | 5second max.   |
| 300%                | 0.2second max. |

#### Specifications

| Part No.      | Current Rating(A) | Voltage Rating (Vdc) | Interrupting Rating | Typical Cold DCR ( $\Omega$ ) | Typical $I^2t$ ( $A^2Sec$ )* | Marking |
|---------------|-------------------|----------------------|---------------------|-------------------------------|------------------------------|---------|
| 0603TD-1.5A-L | 1.5               | 35                   | 35A @35V            | 0.05                          | 0.082                        | N       |

\*Typical  $I^2t$ : i.e. melting  $I^2t$  at 0.001s of current rating

#### Dimension



#### Packaging

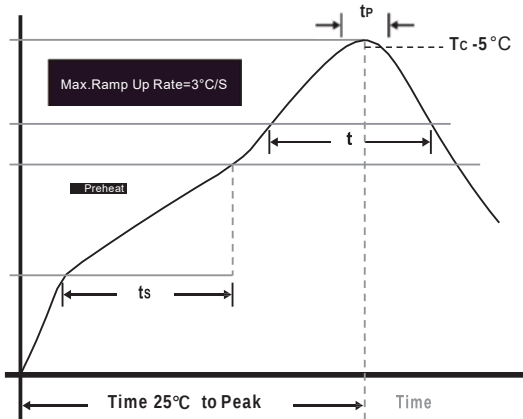
- Quantity: 5, 000pcs
- 8mm wide tape on 178mm (7 inch) diameter reel -specification EIA Standard 481

# Ultra-Thin Fuse | 0.06x0.03"

0603TD-L Series

## Time Delay series Thin Film Chip Fuse

### Soldering Parameters



Wave Soldering: 260°C, 10 seconds max.

Infrared Reflow: 260°C, 30 seconds max.

### IR Reflow Profile

Preheat Heat  
Temperature min (T<sub>min</sub>) 150°C  
Temperature max (T<sub>max</sub>) 200°C  
Time (T<sub>min</sub> to T<sub>max</sub>) (t<sub>s</sub>) 60 - 120 seconds

Average ramp-up rate (T<sub>max</sub> to T<sub>p</sub>) 3°C/second max.

Liquidous temperature (T<sub>L</sub>) 217 °C  
Time at liquidous (t<sub>L</sub>) 60 - 150 seconds

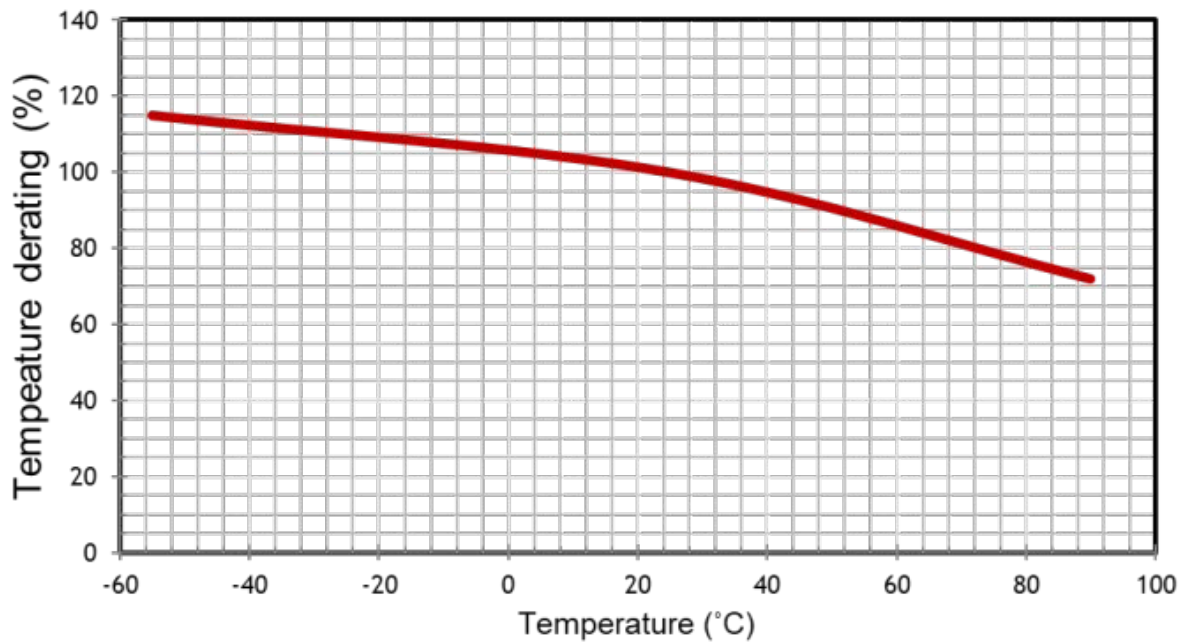
Peak temperature (T<sub>p</sub>) 260°C

Time within 5°C of actual peak Temperature (t<sub>p</sub>) 30 seconds

Average ramp-down rate (T<sub>p</sub> to T<sub>max</sub>) 6°C/second max.

Time 25 °C to peak temperature 8 minutes max.

### Temperature Effect on Current Rating



- Normal ambient temperature: 23+/-3°C
- Operating temperature: -55 ~ 105°C

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## Average Time-Current curve

